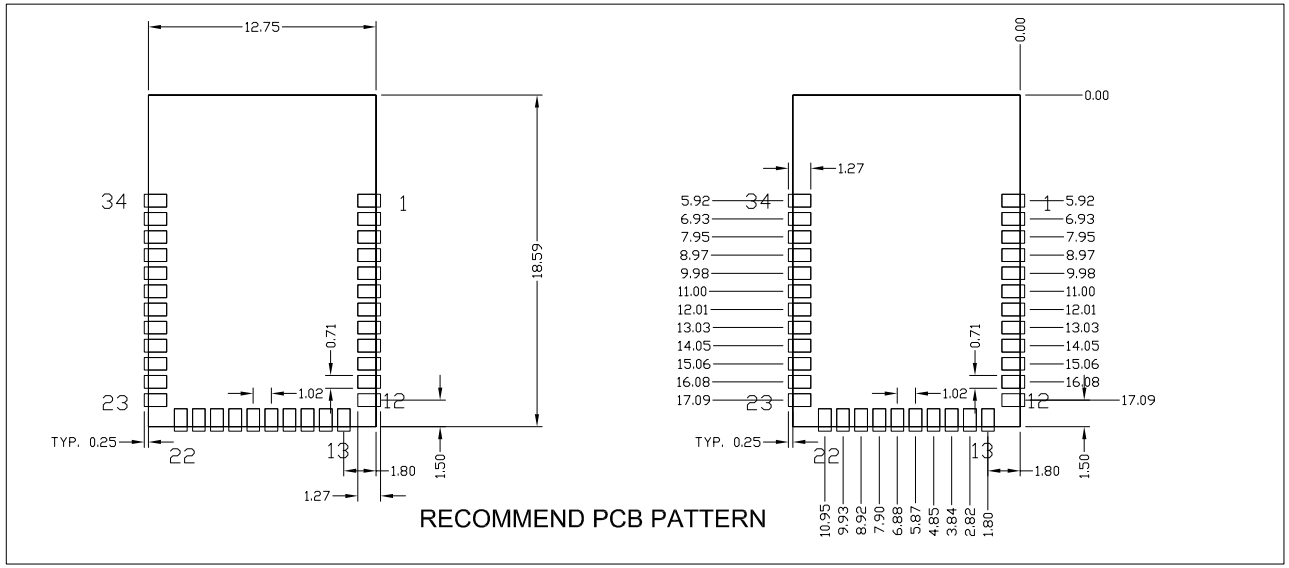
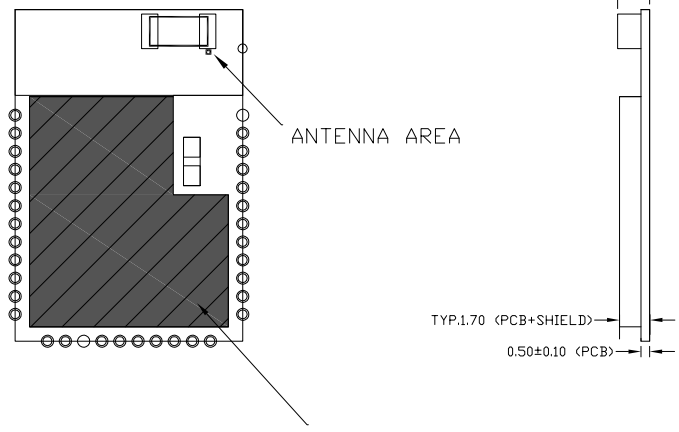
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
0.1	INITIAL RELEASE	WW1812	
0.2	ADD X Y TABLE	WW1821	



RECOMMEND PCB PATTERN

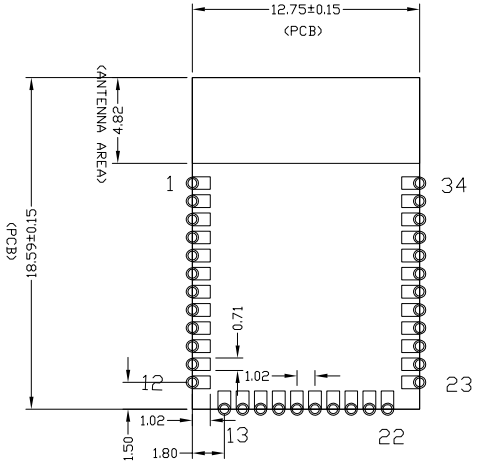
MODULE PAD ASSIGNMENT:

PAD1:VCC
PAD2:GND
PAD3:XRES
PAD4:P33
PAD5:P25
PAD6:P26
PAD7:P38
PAD8:P34/P35/P36
PAD9:P1
PAD10:P0
PAD11:P29
PAD12:P13/P23/P28
PAD13:GND
PAD14:P10/P11
PAD15:P17
PAD16:P7
PAD17:P6
PAD18:P4
PAD19:XTALO_32K
PAD20:XTALI_32K/P15
PAD21:UART_CTS_N
PAD22:UART_RTS_N
PAD23:UART_TXD
PAD24:UART_RXD
PAD25:HOST_WAKE
PAD26:GND
PAD27:GND
PAD28:GND
PAD29:GND
PAD30:GND
PAD31:GND
PAD32:VDDR
PAD33:GND
PAD34:GND

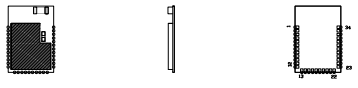


SEEN FROM TOP

SEEN FROM SIDE



SEEN FROM BOTTOM



SCALE 1:1

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN MM	DRAWN:	WW1821
TOLERANCES ON:	CHECKED	
+/- 0.15 MM	ENGRG	
ANGLES +/-0.5 DEGREE	ISSUED	

CYPRESS SEMICONDUCTOR Corp.

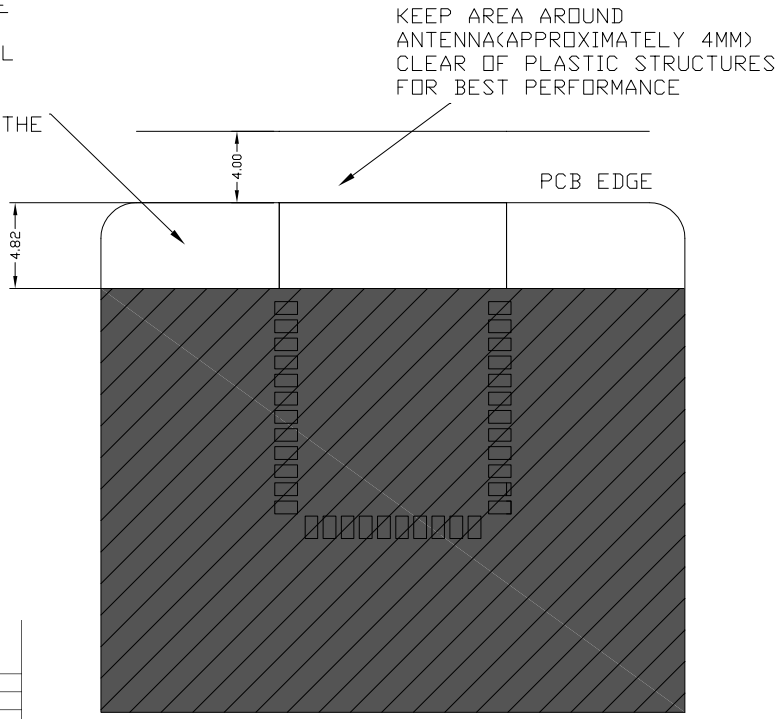
CYBT-483039-02

SIZE	REV NO	DWG NO
	0.2	

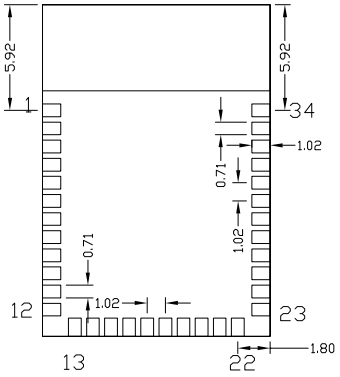
SCALE 5:1 | THE 3RD PROJECTION | SHEET: 1 OF 1

HOST PCB KEEP OUT AREA AROUND ANTENNA

1. TO PLACE THE BLE MODULE AT THE EDGE OF THE HOST BOARD.
2. KEEP OUT THE HOST BOARD ON ALL LAYERS.
3. ADDITIONAL KEEP OUT TO COVER COMPLETE MODULE AREA WILL HAVE THE BEST RF PERFORMANCE/DISTANCE.

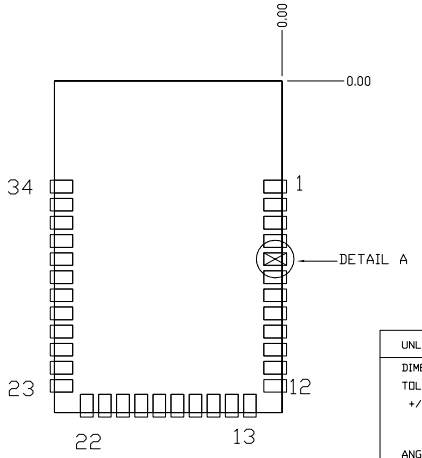


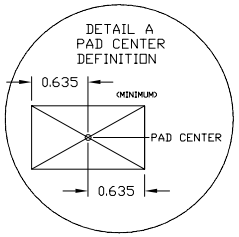
PAD DIMENSION



SOLDER PAD AND LOCATION

Solder Pad (Center of Pad)	Location (X,Y) from Origin (mm)	Dimension from Origin (mil)
1	(0.38, 5.92)	(14.96, 233.07)
2	(0.38, 6.93)	(14.96, 272.83)
3	(0.38, 7.95)	(14.96, 312.99)
4	(0.38, 8.97)	(14.96, 353.15)
5	(0.38, 9.98)	(14.96, 392.91)
6	(0.38, 11.00)	(14.96, 433.07)
7	(0.38, 12.01)	(14.96, 472.83)
8	(0.38, 13.03)	(14.96, 512.99)
9	(0.38, 14.05)	(14.96, 553.15)
10	(0.38,15.06)	(14.96, 592.91)
11	(0.38,16.08)	(14.96, 633.07)
12	(0.38,17.09)	(14.96, 672.83)
13	(1.80,18.21)	(70.87, 716.93)
14	(2.82,18.21)	(111.02, 716.93)
15	(3.84,18.21)	(151.18, 716.93)
16	(4.85,18.21)	(190.94, 716.93)
17	(5.87,18.21)	(231.10, 716.93)
18	(6.88,18.21)	(270.87, 716.93)
19	(7.90,18.21)	(311.02, 716.93)
20	(8.92,18.21)	(351.18, 716.93)
21	(9.93,18.21)	(390.94, 716.93)
22	(10.95,18.21)	(431.10, 716.93)
23	(12.37,17.09)	(487.01, 672.83)
24	(12.37,16.08)	(487.01, 633.07)
25	(12.37,15.06)	(487.01, 592.91)
26	(12.37,14.05)	(487.01, 553.15)
27	(12.37,13.03)	(487.01, 512.99)
28	(12.37,12.01)	(487.01, 472.83)
29	(12.37,11.00)	(487.01, 433.07)
30	(12.37,9.98)	(487.01, 392.91)
31	(12.37,8.97)	(487.01, 353.15)
32	(12.37,7.95)	(487.01, 312.99)
33	(12.37,6.93)	(487.01, 272.83)
34	(12.37,5.92)	(487.01, 233.07)





UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	CYPRESS SEMICONDUCTOR Corp.
DIMENSIONS ARE IN MM	DRAWN:	WW1821	
TOLERANCES ON: +/- 0.20 MM	CHECKED		
	ENGRG		CYBT-483039-02
ANGLES +/-0.5 DEGREE	ISSUED		

SIZE	REV NO	DWG NO
	0.2	

SCALE 5:1 | THE 3RD PROJECTION | SHEET: 2 OF 2